

# **RB048RSM15S**

Schottky Barrier Diode

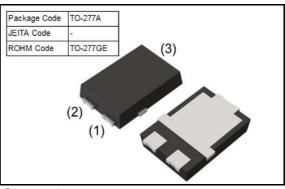
Data sheet

V <sub>R</sub>	150	V
Ι <sub>ο</sub>	8	Α
I <sub>FSM</sub>	160	А

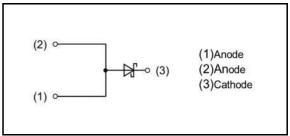
- Features
  High reliability
  Power mold type
  Ultra low I<sub>R</sub>
- Application
   Switching power supply

   Freewheel diode
   Reverse polarity protection
- StructureSilicon epitaxial planar

### Outline



Inner Circuit



Packaging Specifications

• r deraging epocinications					
Packing	Embossed Tape				
Reel Size(mm)	330				
Taping Width(mm)	12				
Quantity(pcs)	4000				
Taping Code	TL1				
Marking	RB048RSM15S				

● Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Limits	Unit
Repetitive peak reverse voltage	$V_{RM}$	Duty≦0.5	150	V
Reverse voltage	V <sub>R</sub>	Reverse direct voltage	150	V
Average rectified forward current	rage rectified forward current $I_0$ 60Hz half sin waveform, resistive load $T_c$ =156°cMax.		8	Α
Peak forward surge current	I <sub>FSM</sub>	60Hz half sin waveform, non-repetitive, T <sub>a</sub> =25°c	160	Α
Junction temperature <sup>(1)</sup>	Tj	-	175	င
Storage temperature	T <sub>stg</sub>	-	-55 <b>~</b> 175	ဇ

Note(1) To avoid occurrence of thermal runaway, actual board is to be designed to fulfill  $dP_d/dT_j < 1/R_{th(j-a)}$ .

#### Attention

Compared with PN junction diodes, Schottky Barrier Diode is generally high reverse current (IR). The reverse loss of the diode might increase as temperature increasing that causes heat-up and further IR. This phenomenon might end up the thermal destruction (thermal runaway). Therefore please give consideration to the reverse loss and the ambient temperature when using this product.

# ullet Electrical Characteristics (T<sub>j</sub>=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward voltage	$V_{F}$	I <sub>F</sub> =8A	-	0.79	0.88	V
Reverse current	I <sub>R</sub>	V <sub>R</sub> =150V	-	0.19	3.7	μA

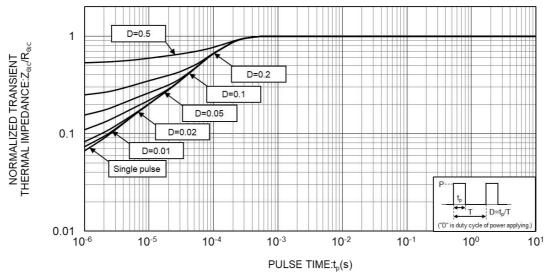
## Thermal Characteristics

Parameter		Min.	Тур.	Max.	Unit
Thermal Resistance (Junction to case) <sup>(1)</sup> (2)	$R_{\theta JC}$	-	-	3	°C/W
Thermal Resistance (Junction to ambient) <sup>(1)</sup>		-	-	90	°C/W

Notes (1) Value is guaranteed by design.

(2) Mounted on 50 x 50 x 1.6mm FR4 board, single-sided copper, 35 $\mu$ m thickness, reference footprint.

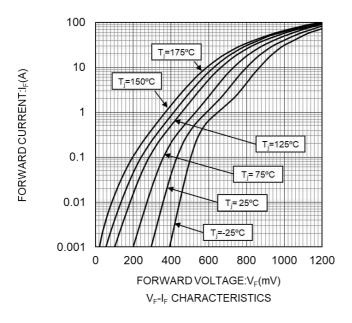
## Characteristic Curves

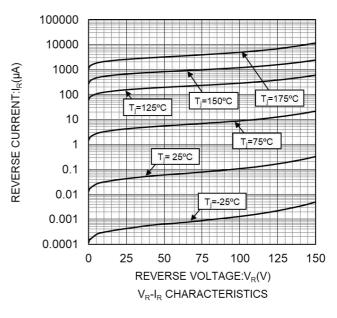


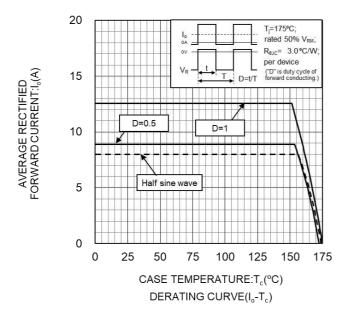
NORMALIZED TRANSIENT THERMAL IMPEDANCE FROM JUNCTION TO CASE (PER DEVICE)

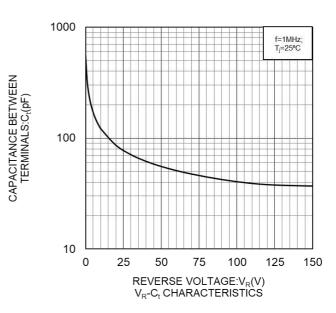
RB048RSM15S Data sheet

## Characteristic Curves



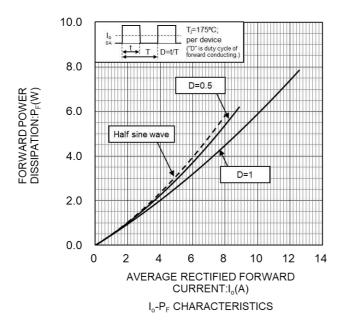


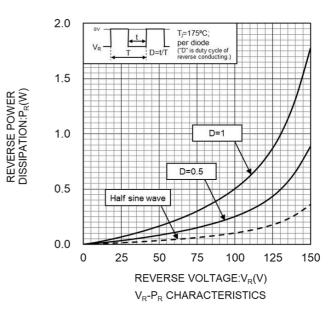


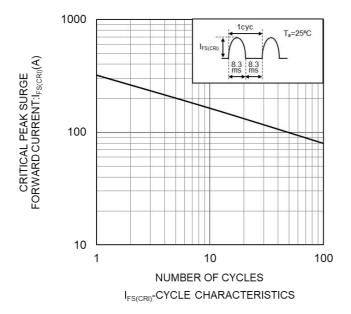


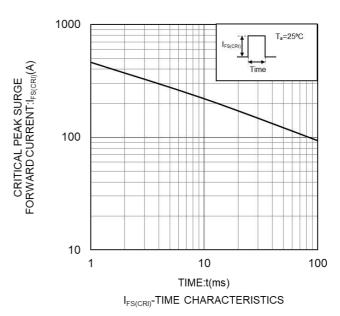
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## Characteristic Curves



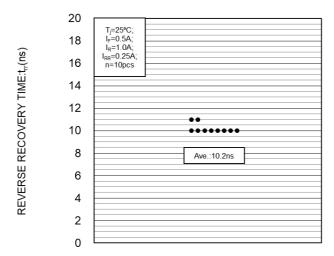






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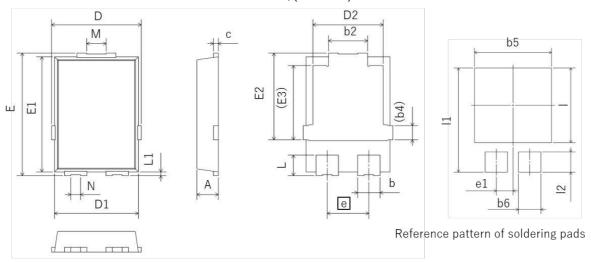
## Characteristic Curves



trr DISPERSION MAP

## Dimensions

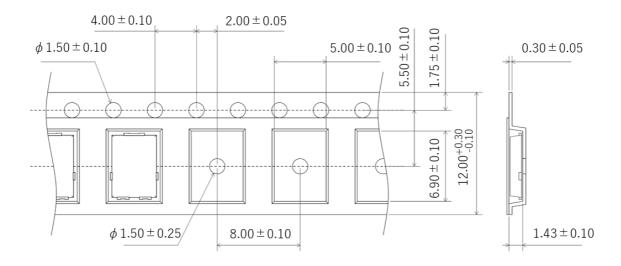
## TO-277A, (TO-277GE)



DIM	Milim	eters	Inc	hes
DIM	Min.	Max.	Min.	Max.
Α	1.00	1.20	0.039	0.047
b	1.05	1.35	0.041	0.053
b2	1.90	2.20	0.075	0.087
b4	0.	75	0.0	30
С	0.15	0.40	0.006	0.016
D	4.45	4.75	0.175	0.187
D1	4.25	4.35	0.167	0.171
D2	3.40	3.70	0.134	0.146
E	6.35	6.65	0.250	0.262
E1	6.05	6.15	0.238	0.242
E2	4.40	4.80	0.173	0.189
E3	3.	94	0.1	55
е	2.	13	0.0	84
L	0.94	1.24	0.037	0.049
L1	0.05	0.35	0.002	0.014
М	0.65	1.15	0.026	0.045
N	0.25	0.75	0.010	0.030

DIM	Milimeters	Inches
DIINI	Typ.	Тур.
b5	4.80	0.189
b6	1.40	0.055
e1	1.04	0.041
1	4.72	0.186
11	6.80	0.268
12	1.27	0.050

## ● Taping (Unit:mm)



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JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	СГУССШ
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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